

# NCE N-Channel Enhancement Mode Power MOSFET

### Description

The NCE3065K uses advanced trench technology and design to provide excellent  $R_{DS(ON)}$  with low gate charge. It can be used in a wide variety of applications.

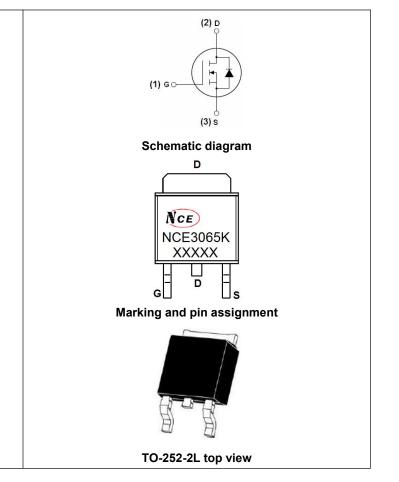
#### **General Features**

- V<sub>DS</sub> =30V,I<sub>D</sub> =65A
  - $R_{DS(ON)}$  <5.2m $\Omega$  @ V<sub>GS</sub>=10V
  - $R_{DS(ON)} < 11m\Omega @ V_{GS}=5V$
- High density cell design for ultra low Rdson
- Fully characterized avalanche voltage and current
- Good stability and uniformity with high EAS
- Excellent package for good heat dissipation

#### Application

- Power switching application
- Hard switched and high frequency circuits
- Uninterruptible power supply

#### 100% UIS TESTED!



#### Package Marking and Ordering Information

Device Marking	Device	Device Package	Reel Size	Tape width	Quantity
NCE3065K	NCE3065K	TO-252-2L	-	-	-

#### Absolute Maximum Ratings (Tc=25°Cunless otherwise noted)

Parameter	Symbol	Limit	Unit
Drain-Source Voltage	VDS	30	V
Gate-Source Voltage	Vgs	±20	V
Drain Current-Continuous	ID	65	A
Drain Current-Continuous(Tc=100℃)	I <sub>D</sub> (100℃)	46	A
Pulsed Drain Current	I <sub>DM</sub>	200	A
Maximum Power Dissipation	PD	65	W
Derating factor		0.43	W/°C
Single pulse avalanche energy (Note 5)	E <sub>AS</sub>	150	mJ
Operating Junction and Storage Temperature Range	T <sub>J</sub> ,T <sub>STG</sub>	-55 To 175	°C

#### **Thermal Characteristic**

Thermal Resistance, Junction-to-Case <sup>(Note 2)</sup>	Rejc	2.3	°C/W	
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#### Electrical Characteristics (TC=25°C unless otherwise noted)

Parameter	Symbol	Condition	Min	Тур	Max	Unit	
Off Characteristics		,	•				
Drain-Source Breakdown Voltage	BV <sub>DSS</sub>	V <sub>GS</sub> =0V I <sub>D</sub> =250µA	30	-	-	V	
Zero Gate Voltage Drain Current	IDSS	V <sub>DS</sub> =30V,V <sub>GS</sub> =0V	-	-	1	μA	
Gate-Body Leakage Current	I <sub>GSS</sub>	V <sub>GS</sub> =±20V,V <sub>DS</sub> =0V	-	-	±100	nA	
On Characteristics (Note 3)	·						
Gate Threshold Voltage	V <sub>GS(th)</sub>	V <sub>DS</sub> =V <sub>GS</sub> ,I <sub>D</sub> =250µA	1	1.6	2.5	V	
Ducin Courses On State Decistories		V <sub>GS</sub> =10V, I <sub>D</sub> =20A	-	4.5	5.2	mΩ	
Drain-Source On-State Resistance	R <sub>DS(ON)</sub>	V <sub>GS</sub> =4.5V, I <sub>D</sub> =20A	-	8.2	11		
Forward Transconductance	<b>g</b> Fs	V <sub>DS</sub> =5V,I <sub>D</sub> =20A	20	-	-	S	
Dynamic Characteristics (Note4)	I						
Input Capacitance	Clss		-	1400	-	PF	
Output Capacitance	C <sub>oss</sub>	$V_{DS}$ =15V, $V_{GS}$ =0V,	-	205	-	PF	
Reverse Transfer Capacitance	Crss	F=1.0MHz	-	177	-	PF	
Switching Characteristics (Note 4)	·						
Turn-on Delay Time	t <sub>d(on)</sub>		-	9	-	nS	
Turn-on Rise Time	tr	V <sub>DD</sub> =5V,I <sub>D</sub> =20A	-	8	-	nS	
Turn-Off Delay Time	t <sub>d(off)</sub>	V <sub>GS</sub> =10V,R <sub>GEN</sub> =6Ω	-	28	-	nS	
Turn-Off Fall Time	t <sub>f</sub>		-	5	-	nS	
Total Gate Charge	Qg	V 45V/L 00A	-	32.3	-	nC	
Gate-Source Charge	Qgs	V <sub>DS</sub> =15V,I <sub>D</sub> =20A,	-	4.9	-	nC	
Gate-Drain Charge	Q <sub>gd</sub>	V <sub>GS</sub> =10V	-	6.9	-	nC	
Drain-Source Diode Characteristics	·						
Diode Forward Voltage (Note 3)	V <sub>SD</sub>	V <sub>GS</sub> =0V,I <sub>S</sub> =20A	-	0.85	1.2	V	
Diode Forward Current (Note 2)	ls		-	-	65	Α	
Reverse Recovery Time	trr	TJ = 25°C, I <sub>F</sub> = 20A	-	-	27	nS	
Reverse Recovery Charge	Qrr	di/dt = 100A/µs <sup>(Note3)</sup>	-	-	20	nC	
Forward Turn-On Time	t <sub>on</sub>	Intrinsic turn-on time is negl	igible (turi	n-on is do	ominated b	y LS+LD)	

#### Notes:

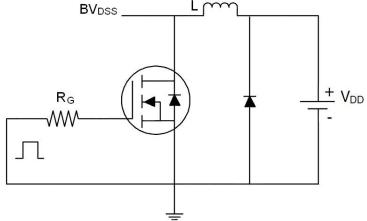
- 1. Repetitive Rating: Pulse width limited by maximum junction temperature.
- **2.** Surface Mounted on FR4 Board,  $t \le 10$  sec.
- **3.** Pulse Test: Pulse Width  $\leq$  300µs, Duty Cycle  $\leq$  2%.
- 4. Guaranteed by design, not subject to production
- **5.** EAS condition:  $Tj=25^{\circ}C$ ,  $V_{DD}=15V$ ,  $V_{G}=10V$ , L=0.5mH,  $Rg=25\Omega$



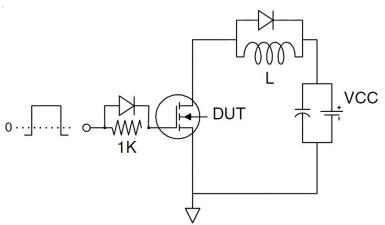
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# Test Circuit

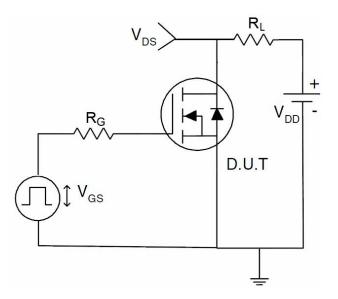
1) E<sub>AS</sub> Test Circuits



2) Gate Charge Test Circuit



3) Switch Time Test Circuit

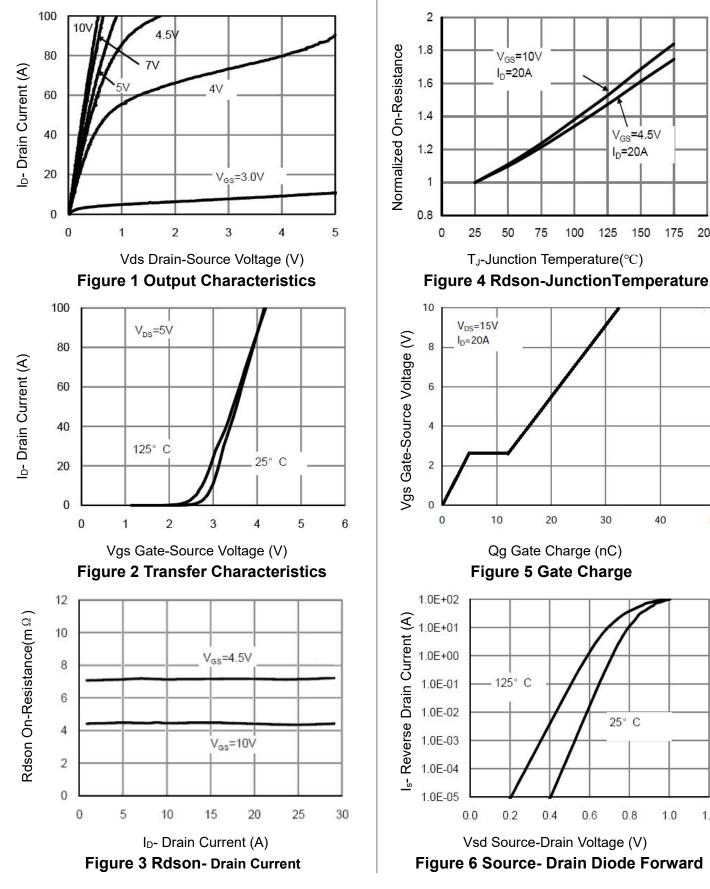




200

50

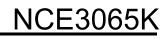
## **Typical Electrical and Thermal Characteristics (Curves)**



1.2



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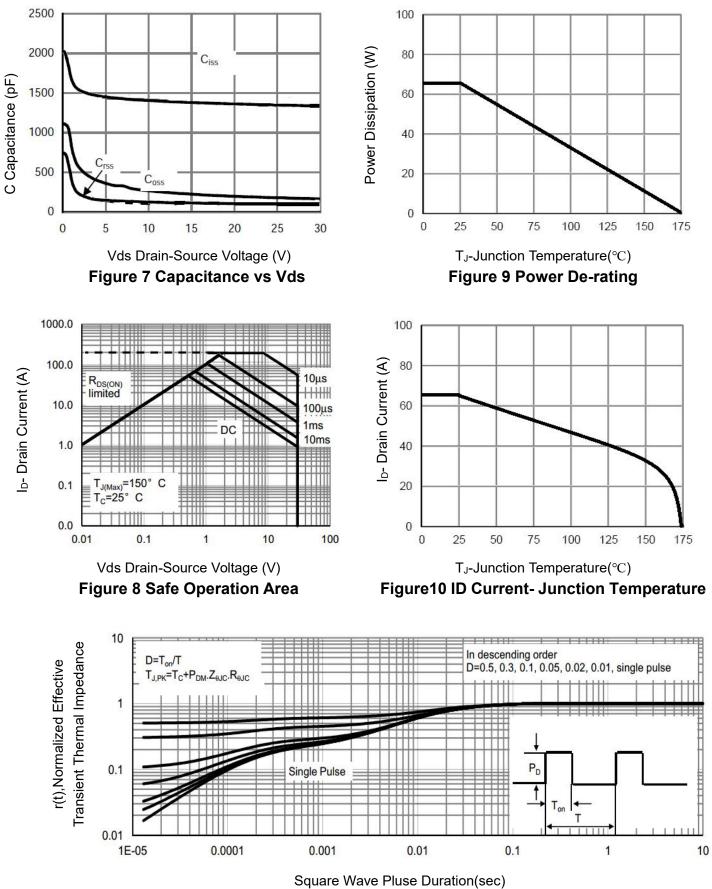
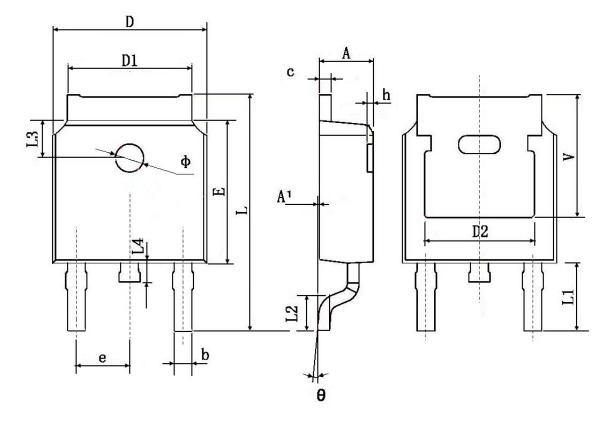


Figure 11 Normalized Maximum Transient Thermal Impedance



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## **TO-252 Package Information**



Symbol	Dimensions	In Millimeters	Dimensions In Inches		
Symbol	Min.	Max.	Min.	Max.	
А	2.200	2.400	0.087	0.094	
A1	0.000	0.127	0.000	0.005	
b	0.660	0.860	0.026	0.034	
С	0.460	0.580	0.018	0.023	
D	6.500	6.700	0.256	0.264	
D1	5.100	5.460	0.201	0.215	
D2	4.830 TYP.		0.190 TYP.		
E	6.000	6.200	0.236	0.244	
е	2.186	2.386	0.086	0.094	
L	9.800	10.400	0.386	0.409	
L1	2.900 TYP.		0.114 TYP.		
L2	1.400	1.700	0.055	0.067	
L3	1.600 TYP.		0.063 TYP.		
L4	0.600	1.000	0.024	0.039	
Φ	1.100	1.300	0.043	0.051	
θ	0°	8°	0°	8°	
h	0.000	0.300	0.000	0.012	
V	5.350	TYP.	0.211 TYP.		

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